

Average Weight: 11.2g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.50736	4.53
	Silicon	7440-21-3	100.00		0.50736	
Solder Bump					0.00336	0.03
	Tin	7440-31-5	63.00		0.0021168	
	Lead	7439-92-1	37.00		0.0012432	
Underfill					0.05824	0.52
	Silica	60676-86-0	70.00		0.040768	
	Epoxy Resin A	9003-36-5	20.00		0.011648	
	Epoxy Resin B	25068-38-6	3.00		0.0017472	
	Hardener	19900-65-3	7.00		0.0040768	
Heat Sink					7.32928	65.44
	Copper	7440-50-8	99.97		7.327081216	
	Nickel	7440-02-0	0.03		0.002198784	
Solder Paste					0.05264	0.47
	Tin	7440-31-5	95.50		0.0502712	
	Silver	7440-22-4	4.00		0.0021056	
	Copper	7440-50-8	0.50		0.0002632	
Substrate					2.46512	22.01
	Copper	7440-50-8	47.61	Metal layer	1.173643632	
	Nickel	7440-02-0	0.51	Metal layer	0.012572112	
	Gold	7440-57-5	0.11	Metal layer	0.002711632	
	BT (core)	N/A	27.54		0.678894048	
	Glass fiber	N/A	10.35		0.25513992	
	Halogen fire retardant	N/A	5.25		0.1294188	
	Solder mask	N/A	8.63		0.212739856	
Solder Balls					0.784	7.00
	Tin	7440-31-5	95.50		0.74872	
	Silver	7440-22-4	4.00		0.03136	
	Copper	7440-50-8	0.50		0.00392	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/14/06	1.0	Initial Xilinx release.
8/15/06	1.1	100% Material Declaration.
9/27/06	1.2	Updated component descriptions.
7/20/10	1.3	Updated Heat Sink substance description.

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